SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Shielded SMD Power Inductor	ABC'S DWG NO.	SS0805□□□□F□-□□□		
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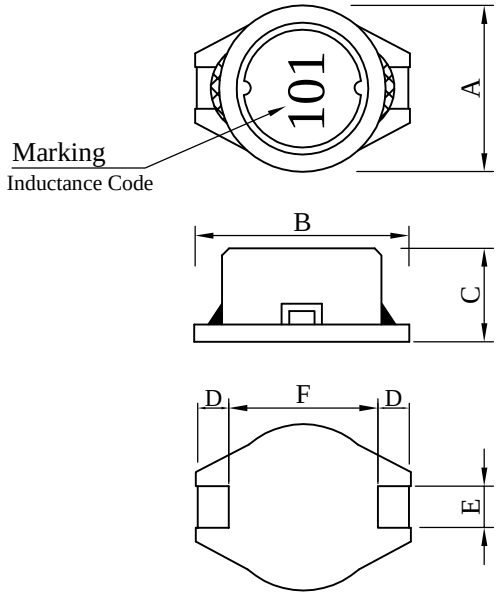
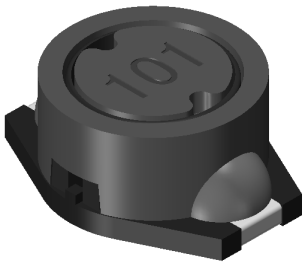
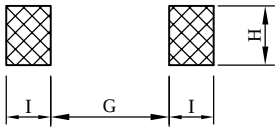
Ⅰ．Configuration and dimensions：







(PCB Pattern)

Unit：m/m

A	B	C	D	E	F	G	H	I
8.00±0.30	10.50±0.30	4.50±0.30	2.10±0.20	2.00±0.20	6.00±0.30	5.70 ref.	2.20 ref.	2.40 ref.

Ⅱ．Description：

a．Ferrite drum core construction.

b．Magnetically shielded.

c．Enamelled copper wire：F class

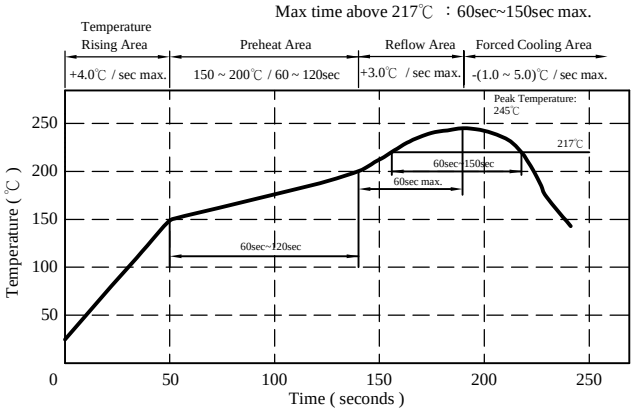
d．Product weight： 0.83g（ref.）

e．Moisture sensitivity Level 1

f．Products comply with RoHS' requirements

g．Halogen free available

Peak Temp：245℃ max.
Max. Peak Temp - 5℃：30sec max.
Max time above 217℃ ：60sec~150sec max.



Ⅲ．General specification：

a．Storage temp.：-40℃ ----+125℃

b．Operating temp.：-40℃----+125℃

(Temp. rise included)

c．Resistance to solder heat：245℃.10 secs.

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Ⅳ．Electrical characteristics：

DWG No.	Inductance (μH)	Q ref.	Test Freq. (Hz)		SRF (MHz) nom	RDC (Ω) max	IDC (A) max
			L	Q			
SS08052R2MF□-□□□	2.2±20%	18	1k	7.960M	75.00	0.040	2.50
SS08053R9MF□-□□□	3.9±20%	20	1k	7.960M	50.00	0.055	2.10
SS08055R6MF□-□□□	5.6±20%	20	1k	7.960M	40.00	0.065	1.95
SS08058R2MF□-□□□	8.2±20%	19	1k	7.960M	32.00	0.080	1.75
SS0805100MF□-□□□	10.0±20%	40	1k	2.520M	28.00	0.100	1.50
SS0805120MF□-□□□	12.0±20%	40	1k	2.520M	24.00	0.120	1.40
SS0805150MF□-□□□	15.0±20%	40	1k	2.520M	22.00	0.140	1.30
SS0805180YF□-□□□	18.0±15%	40	1k	2.520M	19.00	0.160	1.20
SS0805220YF□-□□□	22.0±15%	38	1k	2.520M	17.00	0.180	1.10
SS0805270YF□-□□□	27.0±15%	35	1k	2.520M	15.50	0.200	1.00
SS0805330YF□-□□□	33.0±15%	40	1k	2.520M	13.50	0.240	0.92
SS0805390YF□-□□□	39.0±15%	35	1k	2.520M	12.00	0.260	0.84
SS0805470YF□-□□□	47.0±15%	32	1k	2.520M	10.50	0.280	0.75
SS0805560KF□-□□□	56.0±10%	30	1k	2.520M	9.50	0.380	0.68
SS0805680KF□-□□□	68.0±10%	28	1k	2.520M	9.00	0.440	0.60
SS0805820KF□-□□□	82.0±10%	28	1k	2.520M	8.50	0.550	0.54
SS0805101KF□-□□□	100.0±10%	45	1k	0.796M	7.50	0.600	0.50
SS0805121KF□-□□□	120.0±10%	42	1k	0.796M	7.00	0.750	0.45
SS0805151KF□-□□□	150.0±10%	39	1k	0.796M	6.50	0.900	0.40
SS0805181KF□-□□□	180.0±10%	41	1k	0.796M	4.80	1.050	0.35
SS0805221KF□-□□□	220.0±10%	38	1k	0.796M	4.50	1.180	0.30
SS0805271KF□-□□□	270.0±10%	37	1k	0.796M	4.20	1.400	0.27
SS0805331KF□-□□□	330.0±10%	36	1k	0.796M	3.80	1.800	0.24
SS0805471KF□-□□□	470.0±10%	34	1k	0.796M	3.50	2.250	0.20
SS0805561KF□-□□□	560.0±10%	32	1k	0.796M	3.00	3.000	0.18
SS0805681KF□-□□□	680.0±10%	32	1k	0.796M	2.80	3.400	0.17
SS0805821KF□-□□□	820.0±10%	35	1k	0.796M	2.50	4.000	0.16
SS0805102KF□-□□□	1000.0±10%	35	1k	0.252M	2.20	5.000	0.15

1). □：Packaging information：□ Code

2). "-□□□"：Reference code

3). Electrical specifications at 25℃

4). IDC base on Temp. rise 40℃ max.

& △L/L0A=10% max.

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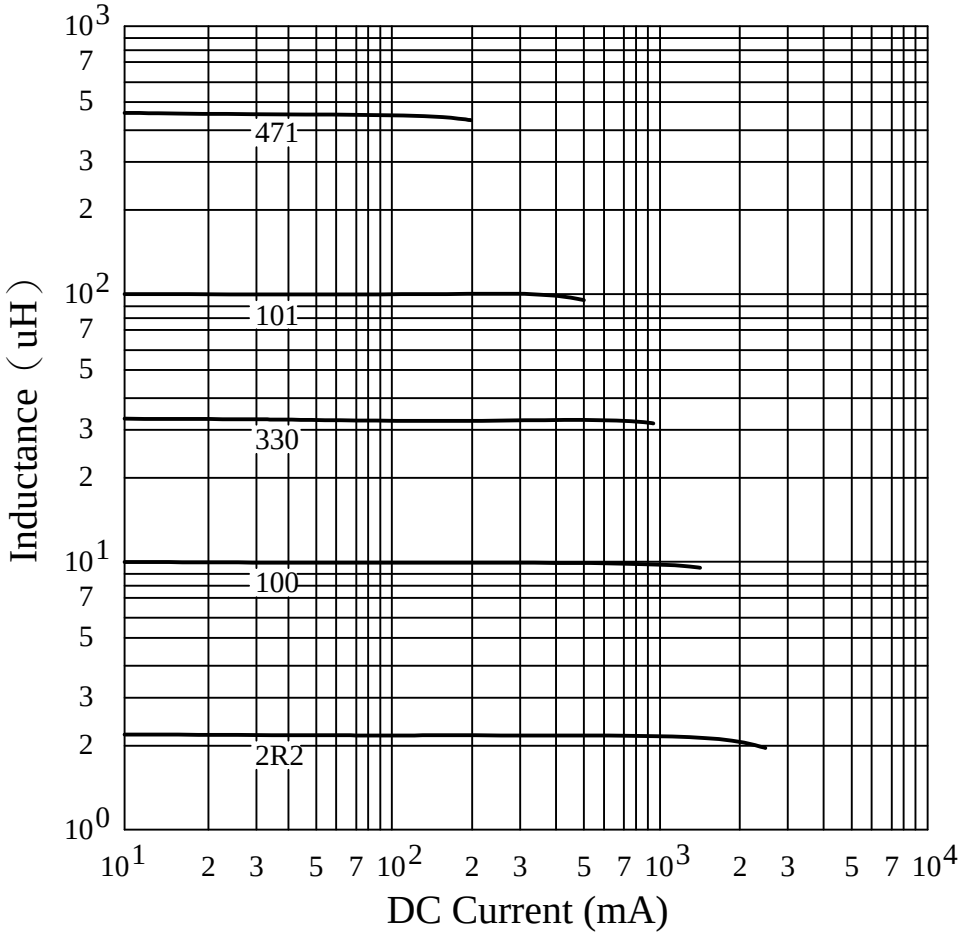
V ．Curve：



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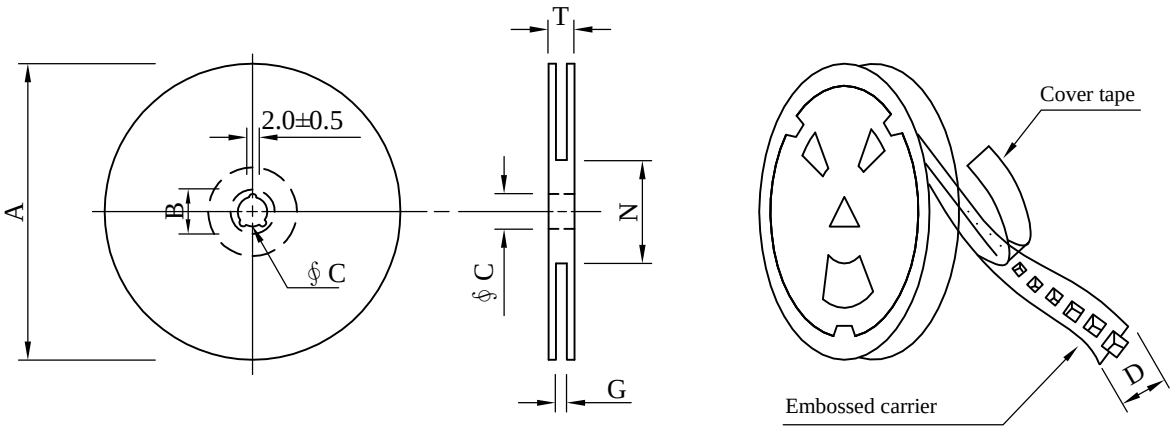
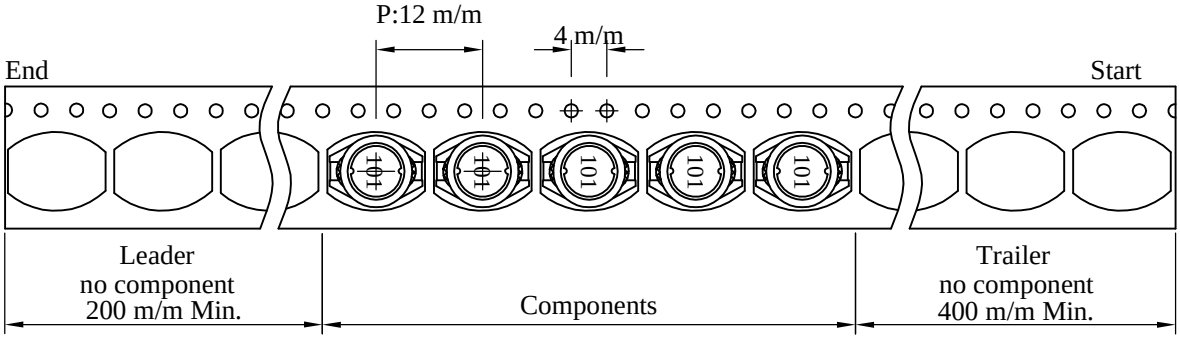
Ⅵ．Packaging information：

(1) Configuration



※Carrier tape width : D



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(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
13 - 16	330	21±0.8	13±0.5	16	18^{+0}	50^{-0}	22.4

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
B	1,000	1240	13 - 16	6,000	6.9	38 x 37 x 22

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Ⅶ．Reliability test：

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125±2℃ 2.Time:96±2 hours.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
2.Temperature Cycling	JESD22-A 104	1.Temperature: -40℃ ~ +125℃ 2.Number of cycle:100 cycle 3.Dwell time:30 minutes	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
3.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature：85±2 ℃ 2.Humidity: 85% RH. 3.Time:96±2 Hours	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
4.Operational Life	JESD22-A 108	1.Temperature: 125℃ (Temp. rise included) 2.Time:96±2 hours. 3.Rated current	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
5.External Visual	JESD22-B 101 & MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.Clear marking. 3.No crack.
6.Physical Dimensions	JESD22-B 100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Resistance to solvents	MIL-STD-202 Method 215	Immerse into solvent for 3±0.5 minutes & brush 10 times for 3 cycles.	1.No body change in apperarance. 2.No marking blurred. 3.Inductance shall not change more than ±20%.
8.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitued : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
9.Resistance To Soldering Heat Test	MIL-STD-202 Method 210 & J-STD020D.1	1.Highest temperature：245±5℃. 2.Time（temp.≧ 217℃）：60~150 Second. 3.IR reflow times：3 times.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
10.Saturation Current	JIS C 6436 & User SPEC.	1.Applied rated current for 5 second. 2.Saturation current	Inductance shall not drop more than 10% max.
11.Over load	JIS C 6436 & User SPEC.	1.Applied one and half rated current for a period of 5 minutes. 2.Rated current	No electrical or mechanical damage
12.Temperature Rise Current	JIS C 6436 & User SPEC.	1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current	Surface temperature rise is less than 40℃ max.
13.Solderability Test	J-STD-002 & JESD22-B 102	1.Baking in pre-testing： 150±5℃ / 16Hours±30 min. 2.Peak temperature：240±5℃ 3.Time（temp.≧217℃）：60~150 second. 4.IR reflow times：1 times.	More than 95% soldering coverage min on terminations.
14.Electrical Characteriazation	MIL-STD-202 Method 304 & User SPEC.	1.Operating temperature：-40℃~125℃ 2.Room temperature：25℃.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
15.Drop	CNS-C6354 & GB/T 2423.8	1.Products shall be mounted on SPEC. PCB and dropped down from a height of 1m 2.Drop total time：6 time (Every side of sample drop 2 time)	1. Adhesion on PCB shall be enough. 2. Product appearance shall not break. 3. No electrical damage.
16.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds.	After test, inductors shall be no mechanical damage.